accepts 2 pieces 100mm wafers parallel

heated area:	220 mm x 155 mm
Part fixture:	2 vacuum holes in the heated plate
Temperature Range:	up to 250 °C
Ramp-up rate:	max. 25 K/min
Ramp-down rate:	max. 10 K/min
Cool down:	controlled cool down
Programming:	programmable with up to 16 segments (heating and cooling)
Interface to PC:	USB interface and PC-Windows Software (as option) for programming, program administration and monitoring
Cover:	with cover protection for connection to exhaust (solvent vapors) (height under cover: 80mm)
Leveling feet:	adjustable